## **Small Signal Diodes**

## MMBD1201 - MMBD1205

#### **Features**

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### ABSOLUTE MAXIMUM RATINGS (Note 1, Note 2)

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Paramete	Value	Unit		
$V_{RRM}$	Maximum Repetitive Re Voltage	100	<b>V</b>		
I <sub>F(AV)</sub>	Average Rectified Forwa	200	mA		
I <sub>FSM</sub>	I <sub>FSM</sub> Non-Repetitive Peak Forward Surge		1.0	Α	
	Current	Pulse Width = 1.0 μs	2.0		
T <sub>STG</sub>	Storage Temperature Range		-55 to + 150	°C	
$T_J$	Operating Junction Temperature		150	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. ON Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

#### THERMAL CHARACTERISTICS

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

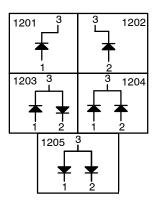
Symbol	Parameter	Value	Unit
P <sub>D</sub>	Power Dissipation	350	mW
	Derate Above 25°C	2.8	mW/°C
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W



#### ON Semiconductor®

www.onsemi.com

#### **CONNECTION DIAGRAM**





SOT-23 CASE 318-08

#### **MARKING DIAGRAM**



2x = Specific Device Code

x = 4, 5, 6, 7, 8

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBD1201,	SOT-23	3000 /
MMBD1202,	(Pb-Free	Tape & Reel
MMBD1203,	Halide Free)	
MMBD1204,		
MMBD1205		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Downloaded from Arrow.com.

#### MMBD1201 - MMBD1205

**ELECTRICAL CHARACTERISTICS** Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
$V_{R}$	Breakdown Voltage	I <sub>R</sub> = 100 μA	100	-	V
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 1.0 mA	550	600	mV
		I <sub>F</sub> = 10 mA	660	740	mV
		I <sub>F</sub> = 100 mA	820	920	mV
		I <sub>F</sub> = 200 mA	0.87	1.0	V
		I <sub>F</sub> = 300 mA	_	1.1	V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 20 V	_	25	nA
		V <sub>R</sub> = 50 V	_	50	nA
		V <sub>R</sub> = 50 V, T <sub>A</sub> = 150°C	_	100	μΑ
C <sub>T</sub>	Total Capacitance	V <sub>R</sub> = 0 V, f = 1.0 MHz	-	2.0	pF
t <sub>rr</sub>	Reverse Recovery Time	$I_F = I_R = 10$ mA, $I_{RR} = 1.0$ mA, $I_{RL} = 100$ $\Omega$	-	4.0	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### TYPICAL PERFORMANCE CHARACTERISTICS

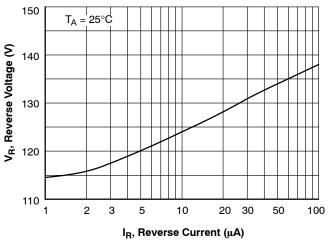


Figure 1. Reverse Voltage vs. Reverse Current  $V_R @\ I_R = 1.0$  to 100  $\mu A$ 

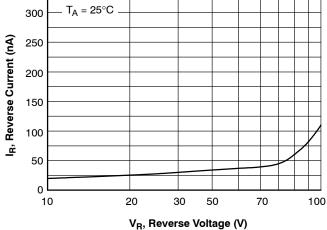
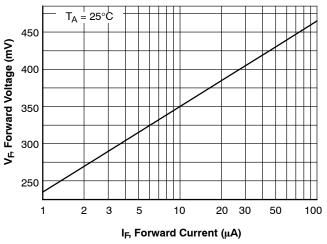


Figure 2. Reverse Current vs. Reverse Voltage  $I_R @V_R = 10 \text{ to } 100 \text{ V}$ 

#### MMBD1201 - MMBD1205

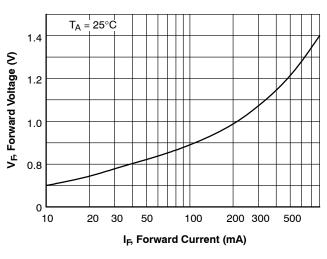
#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)



T<sub>A</sub> = 25°C 700 V<sub>F</sub> Forward Voltage (mV) 650 600 550 500 450 0.1 0.2 0.3 0.5 2 3 5 10 I<sub>F</sub>, Forward Current (mA)

Figure 3. Forward Voltage vs. Forward Current  $V_F @ I_F = 1.0$  to  $100 \mu A$ 

Figure 4. Forward Voltage vs. Forward Current  $V_F \ @ \ I_F = 0.1$  to 10 mA



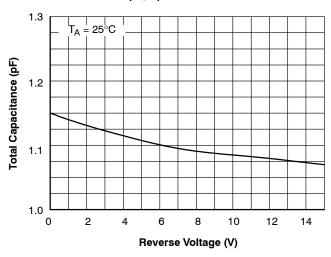
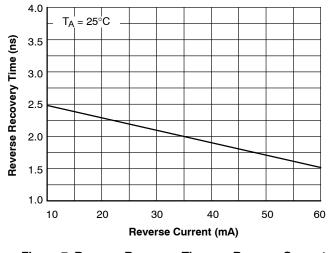


Figure 5. Forward Voltage vs. Forward Current  $V_F @ I_F = 10 \text{ to } 800 \text{ mA}$ 

Figure 6. Total Capacitance vs. Reverse Voltage



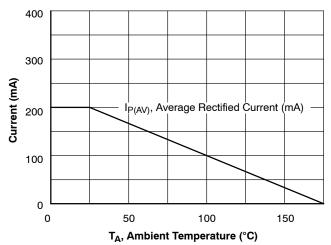


Figure 7. Reverse Recovery Time vs. Reverse Current

Figure 8. Average Rectified Current  $(I_{F(AV)})$  vs. Ambient Temperature  $(T_A)$ 

#### MMBD1201 - MMBD1205

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

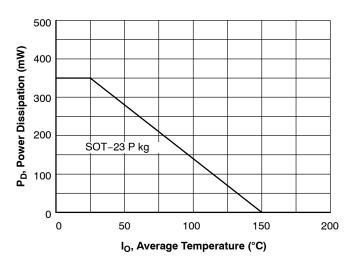


Figure 9. Power Derating Curve

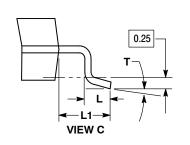


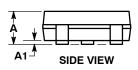
SOT-23 (TO-236) CASE 318-08 **ISSUE AS** 

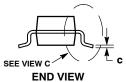
**DATE 30 JAN 2018** 

# SCALE 4:1 D - 3X b

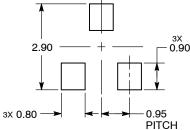
**TOP VIEW** 







#### **RECOMMENDED SOLDERING FOOTPRINT**



DIMENSIONS: MILLIMETERS

STYLE 28: PIN 1. ANODE 2. ANODE

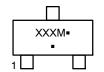
3. ANODE

#### NOTES:

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	O°		10°	O°		10°

#### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	ı	
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE		PIN 1. NO CONNECTION	I PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE		2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE		3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE		PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE		2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN		3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION

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DESCRIPTION:	SOT-23 (TO-236)		PAGE 1 OF 1		

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STYLE 27: PIN 1. CATHODE 2. CATHODE

3. CATHODE

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